



# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Wai-Yi Lien, et al.	§	Examiner:	TBD
Serial No.:	10/823,874	§	Art Unit:	2831
Filed:	April 14, 2004	§	Conf. No.:	6167
For:	Device and Method for Providing Shielding in Radio Frequency Integrated Circuits to Reduce Notice Coupling	§ § § §		

## POWER OF ATTORNEY FOR PATENT APPLICATION

Commissioner For Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

As a representative of the Assignee, Taiwan Semiconductor Manufacturing, Co. Ltd., I hereby appoint the following attorneys to prosecute the above-identified application and to transact all business in the United States Patent and Trademark Office in connection therewith:

Practitioners associated with the Customer Number

42717

Please direct all correspondence and telephone calls to the address associated with the above-mentioned Customer Number.

The undersigned representative for the Assignee certifies that the assignee is the assignee of the entire right, title and interest in the above-identified patent application. A copy of the assignment or other documents in the chain of title are attached.

Executed the \_\_\_\_\_ day of \_\_\_\_\_.

Taiwan Semiconductor Manufacturing Company, Ltd.

*Chien Wei Chou*

Chien Wei Chou  
Director, IP Division

# ASSIGNMENT

WHEREAS, we,

- |     |                  |    |                          |
|-----|------------------|----|--------------------------|
| (1) | Wai-Yi Lien      | of | Hsin-Chu, Taiwan, R.O.C. |
| (2) | Chung-Long Chang | of | Hsin-Chu, Taiwan, R.O.C. |
| (3) | Jhy-Chyurn Guo   | of | Hsin-Chu, Taiwan, R.O.C. |
| (4) | John Chern       | of | Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

## A DEVICE AND METHOD FOR PROVIDING SHIELDING IN RADIO FREQUENCY INTEGRATED CIRCUITS TO REDUCE NOISE COUPLING

for which we have executed an application for Letters Patent of the United States of America,

         of even date filed herewith; and  
  X   filed on April 14, 2004 and assigned application number 10/823,874; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Dated: ✓ Apr. 19, 2004

✓ Wai-Yi Lien  
Inventor Signature

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Dated: ✓ 04/19/2004

✓ [Signature]  
Inventor Signature

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